ALL SHORE INDUSTRIES

ASI-O-177HADDH80/M

No.	Items	Specification	Unit
1	Display Mode	Passive Matrix OLED	-
2	Display Color	65K/262K	-
3	Duty	1/128	-
4	Resolution	160(H) x 128(V)	Pixel
5	Active Area	35.015 (W) x 28.012 (H)	mm^2
6	Outline Dimension	42.70 (W) x 33.40 (H) x 2.01 (D)	mm^3
7	Dot Pitch	0.073 (W) x 0.219 (H)	mm^2
8	Dot Size	0.048 (W) x 0.199 (H)	mm^2
9	Aperture Rate	60	%
10	Driver IC	SSD1353	-
11	Interface	8/9/16/18bit 6800/8080-series parallel, SPI	-
12	Weight	5.92±10%	g

REVISION RECORD

REV NO.	REV DATE	CONTENTS	REMARKS
1.0	2013-08-06	First Release	

CONTENT

■ PHYSICAL DATA

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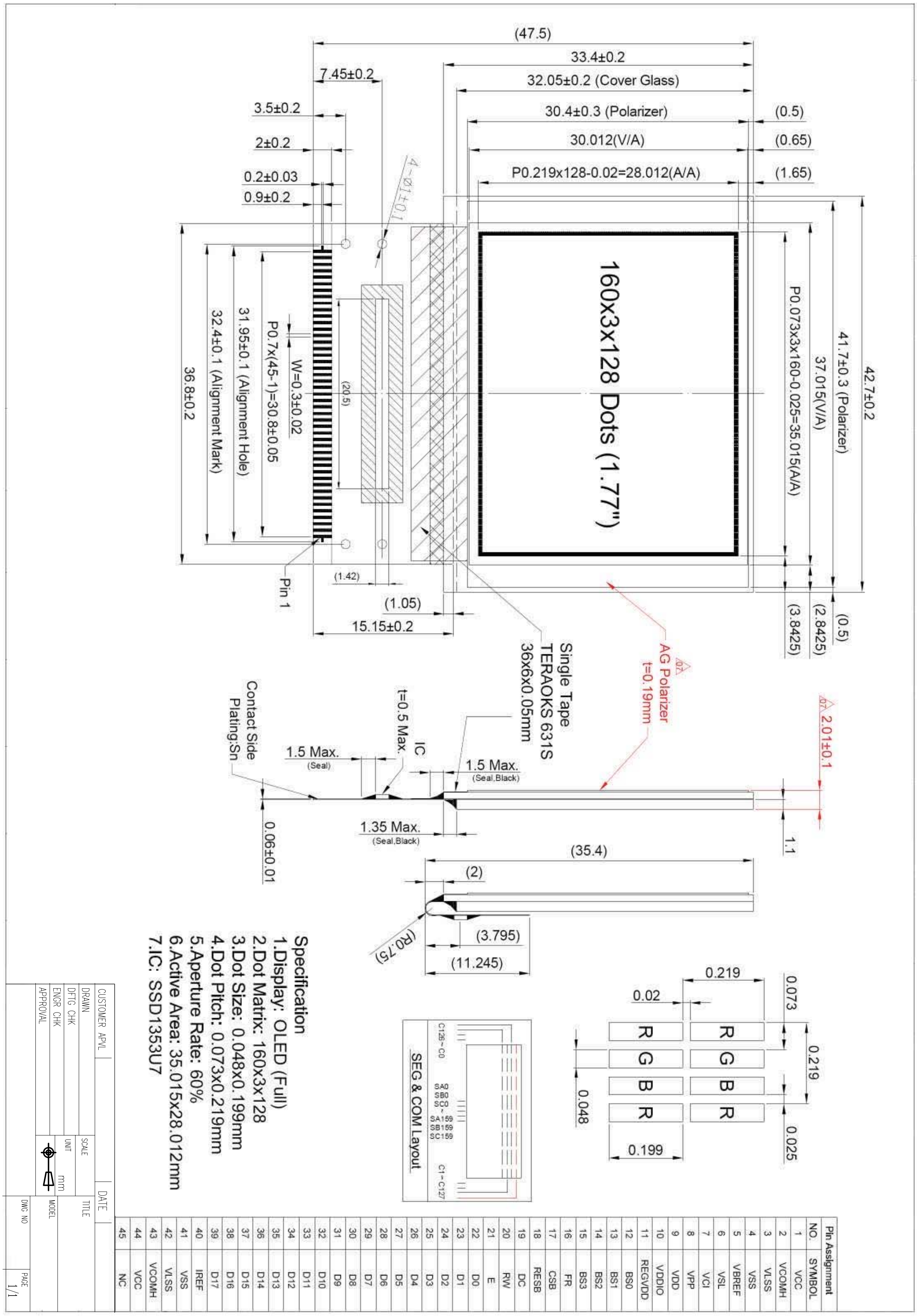
■ EXTERNAL DIMENSIONS



■ ABSOLUTE MAXIMUM RATINGS

Items	Symbol	Min	Typ.	Max	Unit	Notes
Supply voltage	V_{CI}	-0.5	-	3.5	V	-
	V_{CC}	10	-	21	V	-
Operating temperature	T_{OP}	-40	-	70	℃	-
Storage temperature	T_{ST}	-40	-	85	℃	-
Life time(80cd/m^2)	-	12,000	-	-	hour	1
Life time(60cd/m^2)	-	16,000	-	-	hour	2
Humidity	-	-	-	85	%RH	-

Note:

(A) Under Vcc = 17V, Ta = 25°C, 50% RH.

(B) Life time is defined the amount of time when the luminance has decayed to less than 50% of the initial measured luminance.

(1) Setting of 80 cd/m^2 :

- Master contrast setting : 0x0f
- Frame rate : 85Hz
- Duty setting : 1/128

(2) Setting of 60 cd/m^2 :

- Master contrast setting : 0x0b
- Frame rate : 85Hz
- Duty setting : 1/128

■ ELECTRICAL CHARACTERISTICS

◆DC Characteristics

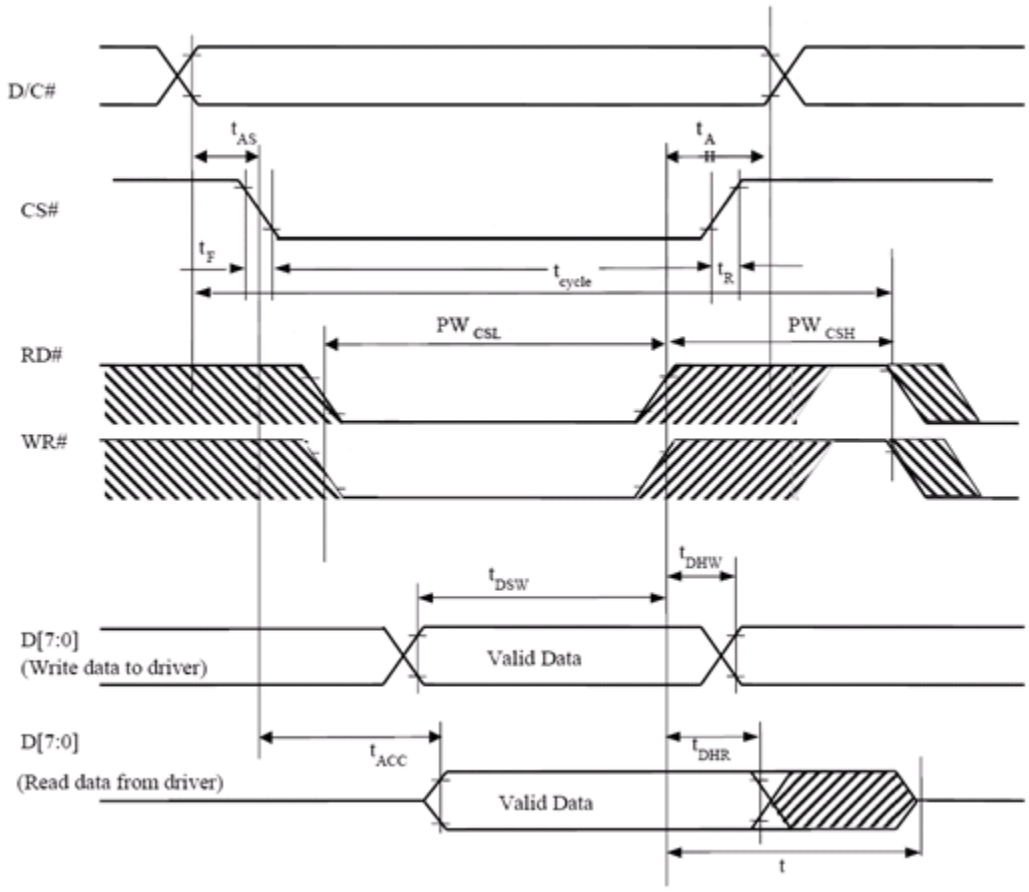
Items	Symbol	Conditions	Min	Typ.	Max	Unit
Driver power supply	V_{CC}		16.5	17.0	17.5	V
Low voltage power supply	V_{CI}		2.4	2.8	3.5	V
Logic I/O operating voltage	V_{DDIO}		1.6	1.8	V_{CI}	V
High level input	V_{IH}	I_{OUT} = 100μA, 3.3MH	0.8 x V_{DDIO}	-	V_{DDIO}	V
Low level input	V_{IL}	I_{OUT} = 100μA, 3.3MH	0	-	0.2x V_{DDIO}	V
High level output	V_{OH}	I_{OUT} = 100μA, 3.3MH	0.9xV_{DDIO}	-	V_{DDIO}	V
Low level output	V_{OL}	I_{OUT} = 100μA, 3.3MH	0	-	0.1xV_{DDIO}	V
Operating current for V_{CI}	I_{CI}	Contrast=FF	-	890	980	uA
Operating current for V_{CC}	I_{CC}	Contrast=FF	-	8.9	10.0	mA
Segment output current setting	I_{SEG}	Contrast=FF	-	160	175	uA
		Contrast=7F	-	80	-	uA

◆AC Characteristics

1. 80XX-Series MPU Parallel Interface Timing Characteristics:

(V_{DD} - V_{SS} = 2.4 to 2.6V, V_{DDIO}=1.6V, T_A = 25°C)

Symbol	Parameter	Min	Typ	Max	Unit
t_{cycle}	Clock Cycle Time	300	-	-	ns
t_{AS}	Address Setup Time	0	-	-	ns
t_{AH}	Address Hold Time	0	-	-	ns
t_{DSW}	Write Data Setup Time	40	-	-	ns
t_{DHW}	Write Data Hold Time	7	-	-	ns
t_{DHR}	Read Data Hold Time	20	-	-	ns
t_{OH}	Output Disable Time	-	-	70	ns
t_{ACC}	Access Time	-	-	140	ns
PW_{CSL}	Chip Select Low Pulse Width (read) Chip Select Low Pulse Width (write)	120 60	-	-	ns
PW_{CSH}	Chip Select High Pulse Width (read) Chip Select High Pulse Width (write)	60 60	-	-	ns
t_R	Rise Time	-	-	15	ns
t_F	Fall Time	-	-	15	ns



8080-series MPU parallel interface characteristics

2. Graphic Display Data Ram Address Map

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 160x132x18bits.

For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software.

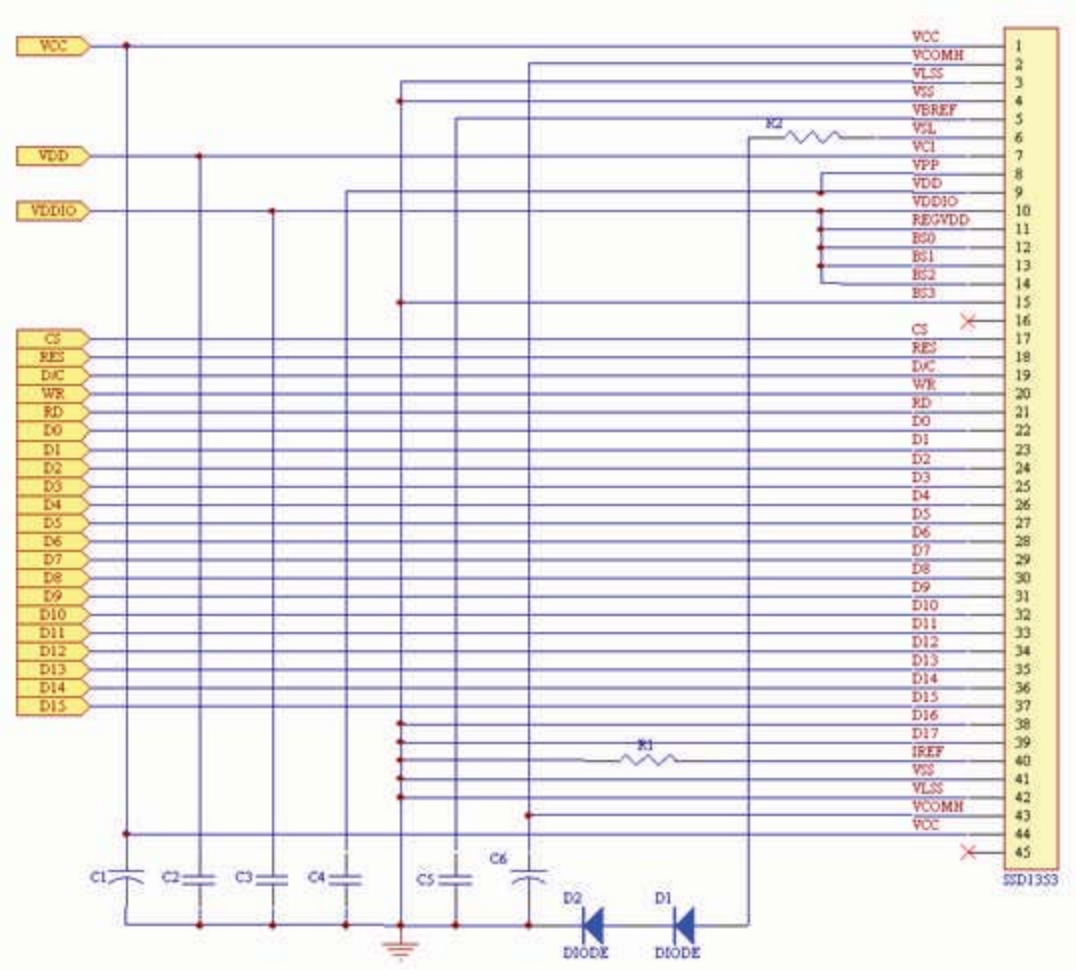
For vertical scrolling of the display, an internal register storing display start line can be set to control the portion of the RAM data to be mapped to the display.

Each pixel has 18-bit data. Each sub-pixels for color A, B and C have 6 bits. The arrangement of data pixel in graphic display data RAM is shown below.

Data Format / Common Address		A5	B5	C5	A5	B5	C5	A5	.....	.....	C5	A5	B5	C5	
		A4	B4	C4	A4	B4	C4	A4	.....	.....	C4	A4	B4	C4	
		A3	B3	C3	A3	B3	C3	A3	.....	.....	C3	A3	B3	C3	
		A2	B2	C2	A2	B2	C2	A2	.....	.....	C2	A2	B2	C2	
		A1	B1	C1	A1	B1	C1	A1	.....	.....	C1	A1	B1	C1	
		A0	B0	C0	A0	B0	C0	A0	.....	.....	C0	A0	B0	C0	Common output
Normal	Remapped														
0	131	6	6	6	6	6	6	6	.....	.....	6	6	6	6	COM0
1	130	6	6	6					.....	.....					COM1
2	129								.....	.....					COM2
3	128								.....	.....					COM3
4	127								.....	.....					COM4
5	126								.....	.....					COM5
6	125			no of bits in this cell					.....	.....					COM6
7	124								.....	.....					COM7
:	:	:	:	:	:	:	:	:	.....	.....	:	:	:	:	
:	:	:	:	:	:	:	:	:	.....	.....	:	:	:	:	
:	:	:	:	:	:	:	:	:	.....	.....	:	:	:	:	
127	4								.....	.....					
128	3								.....	.....					COM128
129	2								.....	.....					COM129
130	1								.....	.....					COM130
131	0								.....	.....					COM131

SEG output	SA0	SB0	SC0	SA1	SB1	SC1	SA2	.....	.....	SC158	SA159	SB159	SA159

3. Application Circuit



Component:

C1, C6 : 4.7 uF/25 ~ 35V Tantalum type capacitor.

C2, C3, C4 : 1uF/ 16V

C5 : 0.1uF/ 16V

R1: 1.2M ohm 1%

R2: 50ohm 1/4W

D1 and D2: RB480K (ROHM)

This circuit is for 8080 16bits interface.

4. Command Table

Refer to IC Spec : SSD1353

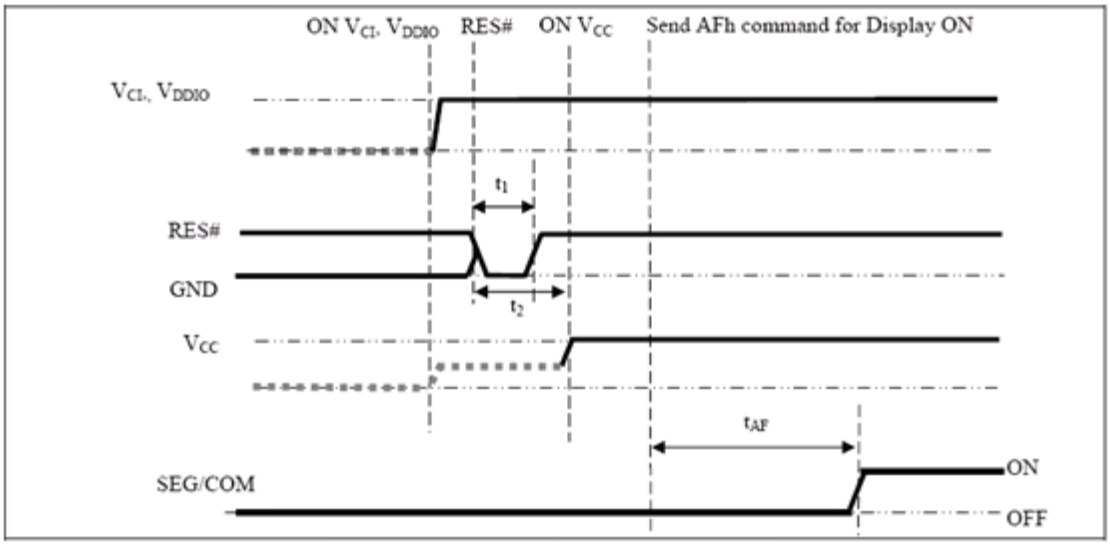
■ TIMING OF POWER SUPPLY

1.POWER ON/OFF SEQUENCE

Power ON sequence:

1. Power ON V_{CI}, V_{DDIO}.
2. After V_{CI}, V_{DDIO} become stable, set RES# pin LOW (logic low) for at least 100us (t_1) and then HIGH(logic high).
3. After set RES# pin LOW (logic low), wait for at least 100us (t_2). Then Power ON V_{CC}.(1)
4. After V_{CC} become stable, send command AFh for display ON. SEG/COM will be ON after 200ms(t_{AF}).

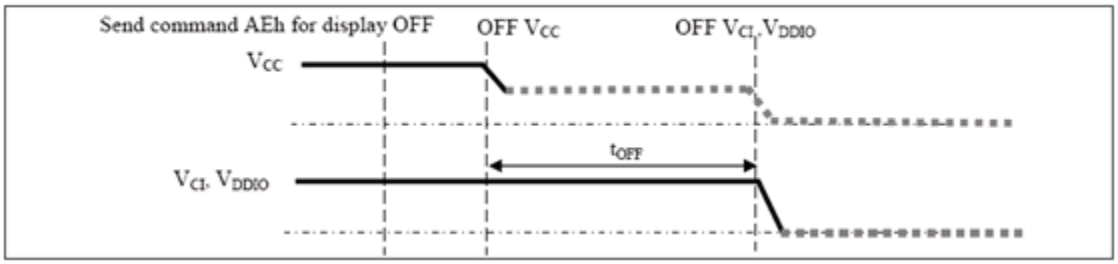
The Power ON sequence.



Power OFF sequence:

1. Send command AEh for display OFF.
2. Power OFF V_{CC}.(1), (2)
3. Wait for t_{OFF}. Power OFF V_{CI}, V_{DDIO}.
   (Where Minimum t_{OFF}=80ms, Typical t_{OFF}=100ms)

The Power OFF sequence



Note:

(1) Since an ESD protection circuit is connected between V_{CI}, V_{DDIO} and V_{CC}, V_{CC} becomes lower than V_{CI} whenever V_{CI}, V_{DDIO} is ON and V_{CC} is OFF as shown in the dotted line of V_{CC} in above figures.

(2) V_{CC} should be disabled when it is OFF.

■ ELECTRO-OPTICAL CHARACTERISTICS (Ta=25℃)

Items		Symbol	Min.	Typ.	Max.	Unit	Remark
Pixel luminance		L	60	80	-	cd /m^2	Display average
Standby mode luminance		L	-	20	-	cd /m^2	
Response time		-	-	10	-	μs	
Normal mode current		-	-	39	41	mA	1
Standby mode current		-	-	3	5	mA	2
Normal mode power consumption		-	-	663	697	mW	1
Standby mode power consumption		-	-	51	85	mW	2
Color Coordinate	White	CIE x	0.27	0.31	0.35	CIE1931	Darkroom
		CIE y	0.29	0.33	0.37		
	Red	CIE x	0.62	0.66	0.70		
		CIE y	0.29	0.33	0.37		
	Green	CIE x	0.26	0.30	0.34		
		CIE y	0.59	0.63	0.67		
	Blue	CIE x	0.10	0.14	0.18		
		CIE y	0.14	0.18	0.22		
Contrast Ratio*		Cr	20000 :1	-	-		Darkroom
Viewing Angle Uniformity		△ θ	160	-	-	Degree	-

Normal mode condition :

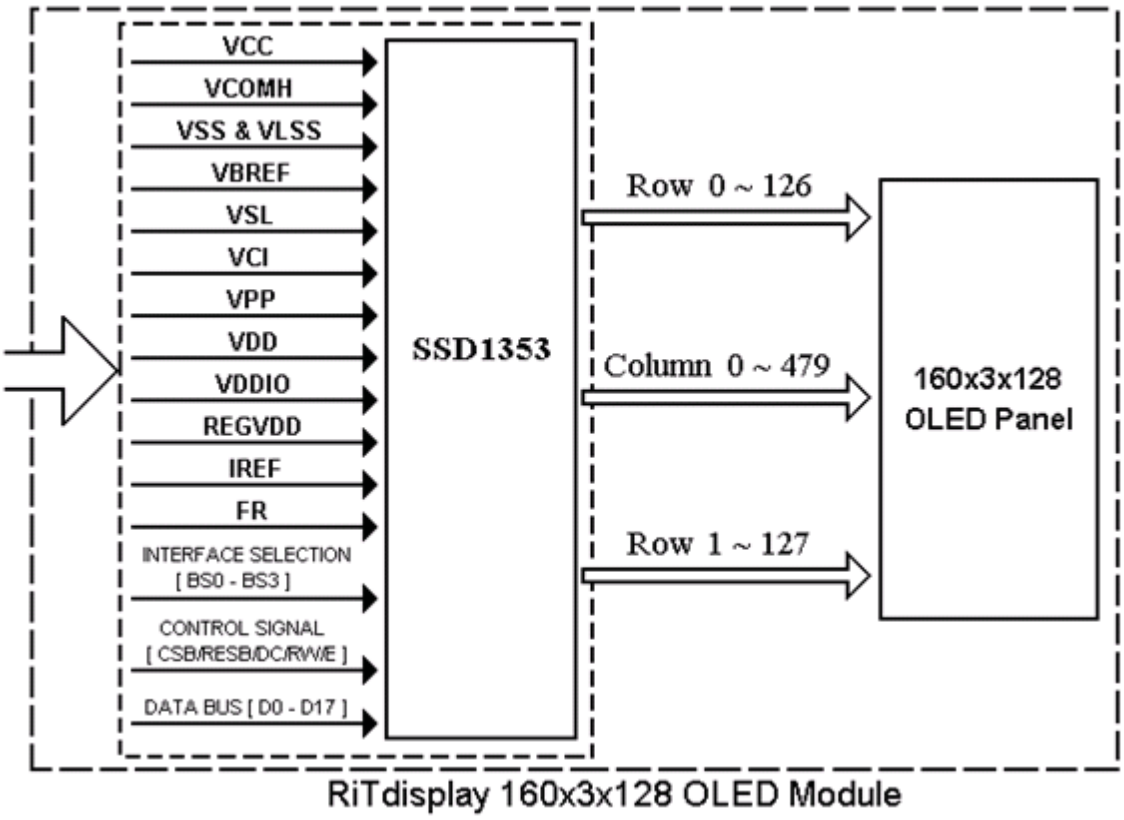
- Driving Voltage : 17V
- Contrast setting : 0x0f
- Frame rate : 85Hz
- Duty setting : 1/128

Standby mode condition :

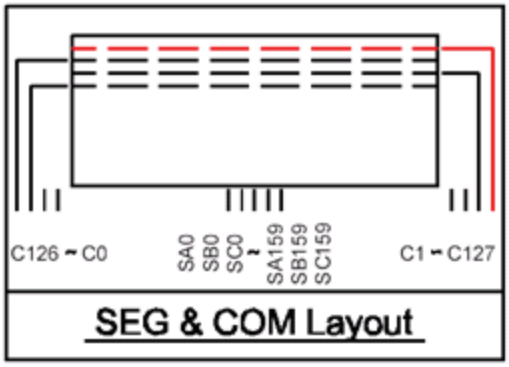
- Driving Voltage : 17V
- Contrast setting : 0x05
- Frame rate : 85Hz
- Duty setting : 1/128

■ INTERFACE PIN CONNECTIONS

1.FUNCTION BLOCK DIAGRAM



2.PANEL LAYOUT DIAGRAM



3.PIN ASSIGNMENTS

PIN NO	PIN NAME	DESCRIPTION
1	VCC	Power supply for panel driving voltage.
2	VCOMH	A capacitor should be connected between this pin and VSS.
3	VLSS	Analog system ground pin.
4	VSS	Ground pin.
5	VBREF	Connect to ground with a capacitor.
6	VSL	This is segment voltage reference pin.
7	VCI	Low voltage power supply.
8	VPP	Connect to VDD.
9	VDD	Power supply input for logic.
10	VDDIO	Power supply for interface logic level.It should be match with the MCU interface voltage level. VDDIO must always be equal or lower than VCI.
11.	REGVDD	Internal VDD regulator selection pin. When this pin is pulled high,internal VDD regulator is enabled. When this pin is pulled low,external VDD regulator is used.
12	BS0	Interface selection pins.
13	BS1	
14	BS2	
15	BS3	
16	FR	It should be kept NC.
17	CSB	This pad is the chip select input. Low active.
18	RESB	This is a reset signal input. Low active.
19	DC	D/C=”H”: Data. D/C=”L”: Command.
20	RW	When connected to 8080-series MPU. WR pin. When RW =”L”: Write signal input. When connected to 6800-series MPU. When RW =”H”: Read. When RW =”L”: Write.
21	E	When connected to 8080-series MPU. RD pin. When E =”L”: Read signal input. When connected to 6800-series MPU. Enable clock input of the 6800 series MPU.
22	D0	18 bit / 16bit / 9bit / 8 bit Data bus I/O.
23	D1	
24	D2	
25	D3	
26	D4	
27	D5	
28	D6	
29	D7	
30	D8	

31	D9	
32	D10	
33	D11	
34	D12	
35	D13	
36	D14	
37	D15	
38	D16	
39	D17	
40	IREF	A resistor should be connected between this pin and VSS.
41	VSS	Ground pin.
42	VLSS	Analog system ground pin.
43	VCOMH	A capacitor should be connected between this pin and VSS.
44	VCC	Power supply for panel driving voltage.
45	NC	No connection.

■ RELIABILITY TESTS

<table>
<tr><th colspan="2">Item</th><th>Condition</th><th>Criterion</th></tr>
<tr><td colspan="2">High Temperature Storage
(HTS)</td><td>85±2℃, 240 hours</td><td rowspan="6">1. After testing, the function test is ok.
2. After testing, no addition to the defect.
3. After testing, the change of luminance should be within +/- 50% of initial value.
4. After testing, the change for the mono and area color must be within (+/-0.02, +/- 0.02) and for the full color it must be within (+/-0.04, +/-0.04) of initial value based on 1931 CIE coordinates.
5. After testing, the change of total current consumption should be within +/- 50% of initial value.</td></tr>
<tr><td colspan="2">High Temperature Operating
(HTO)</td><td>70±2℃, 120 hours</td></tr>
<tr><td colspan="2">Low Temperature Storage
(LTS)</td><td>-40±2℃, 240 hours</td></tr>
<tr><td colspan="2">Low Temperature Operating
(LTO)</td><td>-40±2℃, 120 hours</td></tr>
<tr><td colspan="2">High Temperature / High Humidity Storage
(HTHHS)</td><td>65±3℃, 90%±3%RH, 96 hours</td></tr>
<tr><td colspan="2">Thermal Shock (Non-operation)
(TS)</td><td>-40±2℃ ~ 25℃ ~ 85±2℃
(30min) (5min) (30min)
20cycles</td></tr>
<tr><td>Vibration (Packing)</td><td>10~55~10Hz,amplitude 1.5mm, 1 hour for each direction x, y, z</td><td colspan="2" rowspan="2">1. One box for each test.
2. No addition to the cosmetic and the electrical defects.</td></tr>
<tr><td>Drop (Packing)</td><td>Height : 1 m, each time for 6 sides, 3 edges, 1 angle</td></tr>
</table>

Note： 1) For each reliability test, the sample quantity is 3, and only for one test item.
2) The HTHHS test is requested the Pure Water(Resistance＞10MΩ).

■OUTGOING QUALITY CONTROL SPECIFICATION

◆Standard

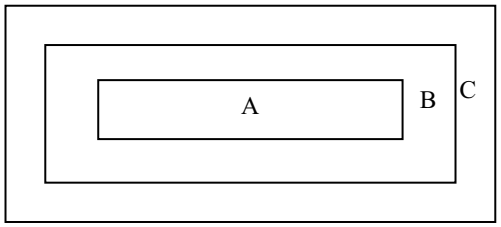
According to GB/T2828.1-2003/ISO 2859-1：1999 and ANSI/ASQC Z1.4-1993, General Inspection Level II.

◆Definition

1 Major defect : The defect that greatly affect the usability of product.

2 Minor defect : The other defects, such as cosmetic defects, etc.

3 Definition of inspection zone:



Zone A: Active Area

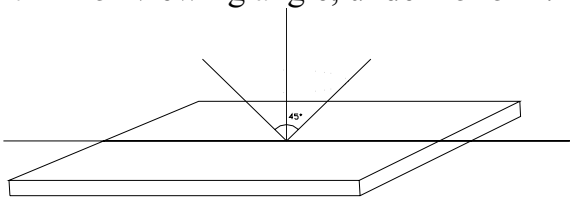
Zone B: Viewing Area except Zone A

Zone C: Outside Viewing Area

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble of quality and assembly to customer`s product.

◆Inspection Methods

1 The general inspection : under 20W x 2 or 40W fluorescent light, about 30cm viewing distance, within 45º viewing angle, under 25±5℃.



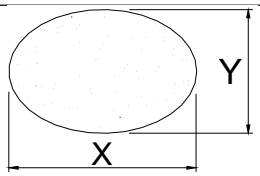
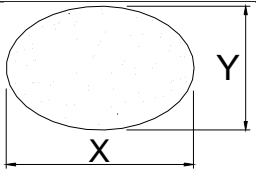
2 The luminance and color coordinate inspection : By PR705 or BM-7 or the equal equipments, in the dark room, under 25±5℃.

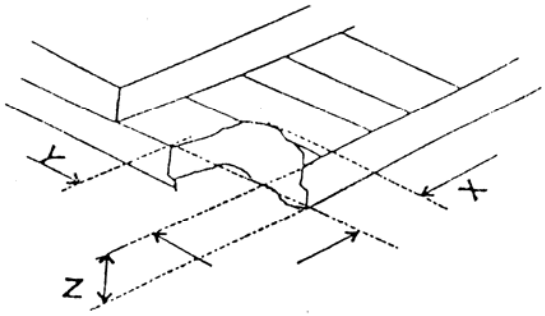
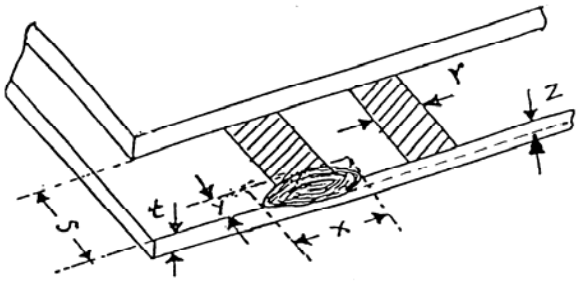
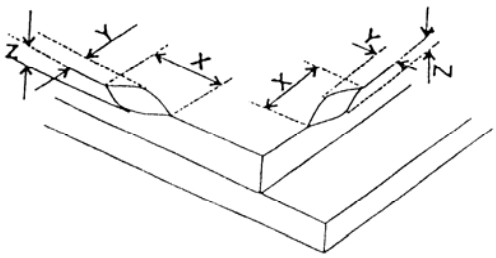
◆Inspection Criteria

1 Major defect : AQL= 0.65

Item	Criterion
Function Defect	1. No display or abnormal display is not accepted
	2. Open or short is not accepted.
	3. Power consumption exceeding the spec is not accepted.
Outline Dimension	Outline dimension exceeding the spec is not accepted.
Glass Crack	Glass crack tends to enlarge is not accepted.

2 Minor Defect : AQL= 1.5

<table>
<tr><td>Item</td><td colspan="4">Criterion</td></tr>
<tr><td rowspan="5">Spot Defect (dimming and lighting spot)</td><td colspan="2">Size (mm)</td><td colspan="2">Accepted Qty</td></tr>
<tr><td colspan="2"></td><td>Area A + Area B</td><td>Area C</td></tr>
<tr><td rowspan="3">  </td><td>Φ≦0.10</td><td colspan="2">Ignored</td></tr>
<tr><td>0.10＜Φ≦0.15</td><td>3</td><td rowspan="2">Ignored</td></tr>
<tr><td>0.15＜Φ≦0. 20</td><td>1</td></tr>
<tr><td colspan="4">Note : Φ= (x + y) / 2</td><td>0.20＜Φ</td><td>0</td></tr>
<tr><td rowspan="5">Line Defect (dimming and lighting line)</td><td>L (Length) : mm</td><td>W (Width) : mm</td><td>Area A + Area B</td><td>Area C</td></tr>
<tr><td>/</td><td>W≦0.03</td><td colspan="2">Ignored</td></tr>
<tr><td>L≦3.0</td><td>0.03＜W≦0.05</td><td>2</td><td rowspan="3">Ignored</td></tr>
<tr><td>L≦2.0</td><td>0.05＜W≦0.08</td><td>1</td></tr>
<tr><td>/</td><td>0.08＜W</td><td>As spot defect</td></tr>
<tr><td colspan="5">Remarks: The total of spot defect and line defect shall not exceed 4 pcs.</td></tr>
<tr><td>Polarizer Stain</td><td colspan="4">Stain which can be wiped off lightly with a soft cloth or similar cleaning is accepted, otherwise, according to the Spot Defect and the Line Defect.</td></tr>
<tr><td rowspan="7">Polarizer Scratch</td><td colspan="4">1. If scratch can be seen during operation, according to the criterions of the Spot Defect and the Line Defect.</td></tr>
<tr><td colspan="4">2. If scratch can be seen only under non-operation or some special angle, the criterion is as below :</td></tr>
<tr><td>L (Length) : mm</td><td>W (Width) : mm</td><td>Area A + Area B</td><td>Area C</td></tr>
<tr><td>/</td><td>W≦0.03</td><td colspan="2">Ignore</td></tr>
<tr><td>5.0＜L≦10.0</td><td>0.03＜W≦0.05</td><td>2</td><td rowspan="3">Ignore</td></tr>
<tr><td>L≦5.0</td><td>0.05＜W≦0.08</td><td>1</td></tr>
<tr><td>/</td><td>0.08＜W</td><td>0</td></tr>
<tr><td rowspan="5">Polarizer Air Bubble</td><td colspan="2">Size</td><td>Area A + Area B</td><td>Area C</td></tr>
<tr><td rowspan="3">  </td><td>Φ≦0.20</td><td colspan="2">Ignored</td></tr>
<tr><td>0.20＜Φ≦0.50</td><td>2</td><td rowspan="3">Ignored</td></tr>
<tr><td>0.50＜Φ≦0.80</td><td>1</td></tr>
<tr><td>0.80＜Φ</td><td>0</td></tr>
</table>

<table>
<tr><td rowspan="4">Glass Defect (Glass Chiped)</td><td>1. On the corner
(mm)
 
<table><tr><td>x</td><td>≤ 2.0</td></tr><tr><td>y</td><td>≤ S</td></tr><tr><td>z</td><td>≤ t</td></tr></table></td></tr>
<tr><td>2. On the bonding edge
(mm)
 
<table><tr><td>x</td><td>≤ a / 2</td></tr><tr><td>y</td><td>≤ s / 3</td></tr><tr><td>z</td><td>≤ t</td></tr></table></td></tr>
<tr><td>3. On the other edges
(mm)
 
<table><tr><td>x</td><td>≤ a / 5</td></tr><tr><td>y</td><td>≤ 1.0</td></tr><tr><td>z</td><td>≤ t</td></tr></table></td></tr>
<tr><td>Note: t: glass thickness ; s: pad width ; a: the length of the edge</td></tr>
<tr><td>TCP Defect</td><td>Crack, deep fold and deep pressure mark on the TCP are not accepted</td></tr>
<tr><td>Pixel Size</td><td>The tolerance of display pixel dimension should be within ±20% of the spec</td></tr>
<tr><td>Luminance</td><td>Refer to the spec or the reference sample</td></tr>
<tr><td>Color</td><td>Refer to the spec or the reference sample</td></tr>
</table>

■ CAUTIONS IN USING OLED MODULE

◆Precautions For Handling OLED Module:

1. OLED module consists of glass and polarizer. Pay attention to the following items when handling:
   i. Avoid drop from high, avoid excessive impact and pressure.
   ii. Do not touch, push or rub the exposed polarizers with anything harder than an HB pencil lead.
   iii. If the surface becomes dirty, breathe on the surface and gently wipe it off with a soft dry cloth. If it is terrible dirty, moisten the soft cloth with Isopropyl alcohol or Ethyl alcohol. Other solvents may damage the polarizer. Especially water, Ketone and Aromatic solvents.
   iv. Wipe off saliva or water drops immediately, contact the polarizer with water over a long period of time may cause deformation.
   v. Please keep the temperature within specified range for use and storage. Polarization degradation, bubble generation or polarizer peeling-off may occur with high temperature and high humidity.
   vi. Condensation on the surface and the terminals due to cold or anything will damage, stain or dirty the polarizer, so make it clean as the way of iii.
2. Do not attempt to disassemble or process the OLED Module.
3. Make sure the TCP or the FPC of the Module is free of twisting, warping and distortion, do not pull or bend them forcefully, especially the soldering pins. On the other side, the SLIT part of the TCP is made to bend in the necessary case.
4. When assembling the module into other equipment, give the glass enough space to avoid excessive pressure on the glass, especially the glass cover which is much more fragile.
5. Be sure to keep the air pressure under 120 kPa, otherwise the glass cover is to be cracked.
6. Be careful to prevent damage by static electricity:
   i. Be sure to ground the body when handling the OLED Modules.
   ii. All machines and tools required for assembling, such as soldering irons, must be properly grounded.
   iii. Do not assemble and do no other work under dry conditions to reduce the amount of static electricity generated. A relative humidity of 50%-60% is recommended.
   iv. Peel off the protective film slowly to avoid the amount of static electricity generated.
   v. Avoid to touch the circuit, the soldering pins and the IC on the Module by the body.
   vi. Be sure to use anti-static package.
7. Contamination on terminals can cause an electrochemical reaction and corrade the terminal circuit, so make it clean anytime.
8. All terminals should be open, do not attach any conductor or semiconductor on the terminals.
9. When the logic circuit power is off, do not apply the input signals.
10. Power on sequence: $V_{DD} \rightarrow V_{PP}$, and power off sequence: $V_{PP} \rightarrow V_{DD}$.
11. Be sure to keep temperature, humidity and voltage within the ranges of the spec, otherwise shorten Module’ s life time, even make it damaged.
12. Be sure to drive the OLED Module following the Specification and Datasheet of IC controller, otherwise something wrong may be seen.

13. When displaying images, keep them rolling, and avoid one fixed image displaying more than 30 seconds, otherwise the residue image is to be seen. This is the speciality of OLED.

◆Precautions For Soldering OLED Module:

1. Soldering temperature : 260°C ± 10°C.
2. Soldering time : 3-4 sec.
3. Repeating time : no more than 3 times.
4. If soldering flux is used, be sure to remove any remaining flux after finishing soldering operation. (This does not apply in the case of a non-halogen type of flux.) It is recommended to protect the surface with a cover during soldering to prevent any damage due to flux spatters.

◆ Precautions For Storing OLED Module:

1. Be sure to store the OLED Module in the vacuum bag with dessicant.
2. If the Module can not be used up in 1 month after the bag being opened, make sure to seal the Module in the vacuum bag with dessicant again.
3. Store the Module in a dark place, do not expose to sunlight or fluorescent light.
4. The polarizer surface should not touch any other objects. It is recommended to store the Module in the shipping container.
5. It is recommended to keep the temperature between 0°C and 30°C , the relative humidity not over 60%.

◆ Limited Warranty

Unless relevant quality agreements signed with customer and law enforcement, for a period of 12 months from date of production, all products (except automotive products) All Shore will replace or repair any of its OLED modules which are found to be functional defect when inspected in accordance with All Shore OLED acceptance standards (copies available upon request). Cosmetic/visual defects must be returned to All Shore within 90 days of shipment. Confirmation of such date should be based on freight documents. The warranty liability of All Shore is limited to repair and/or replacement on the terms above. All Shore will not be responsible for any subsequent or consequential events.

◆Return OLED Module Under Warranty:

1. No warranty in the case that the precautions are disregarded.
2. Module repairs will be invoiced to the customer upon mutual agreement. Modules must be returned with sufficient description of the failures or defects.